



FQB13N06 / FQI13N06

60V N-Channel MOSFET

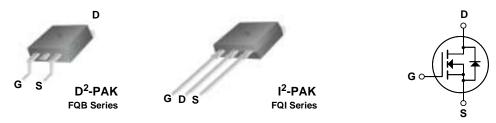
General Description

These N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar stripe, DMOS technology.

This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for low voltage applications such as DC/DC converters, high efficiency switching for power management in portable and battery operated products.

Features

- 13A, 60V, $R_{DS(on)} = 0.135\Omega @V_{GS} = 10 V$
- Low gate charge (typical 5.8 nC)
- Low Crss (typical 15 pF)
- Fast switching
- 100% avalanche tested
- · Improved dv/dt capability
- 175°C maximum junction temperature rating



Absolute Maximum Ratings T_C = 25°C unless otherwise noted

Symbol	Parameter		FQB13N06 / FQI13N06	Units	
V _{DSS}	Drain-Source Voltage		60	V	
I _D	Drain Current - Continuous (T _C = 25°	°C)	13	Α	
	- Continuous (T _C = 100	O°C)	9.2	Α	
I _{DM}	Drain Current - Pulsed	(Note 1)	52	Α	
V _{GSS}	Gate-Source Voltage		± 25	V	
E _{AS}	Single Pulsed Avalanche Energy	(Note 2)	85	mJ	
I _{AR}	Avalanche Current	(Note 1)	13	Α	
E _{AR}	Repetitive Avalanche Energy	(Note 1)	4.5	mJ	
dv/dt	Peak Diode Recovery dv/dt	(Note 3)	7.0	V/ns	
P_{D}	Power Dissipation (T _A = 25°C) *		3.75	W	
	Power Dissipation (T _C = 25°C)		45	W	
	- Derate above 25°C		0.3	W/°C	
T _J , T _{STG}	Operating and Storage Temperature Range		-55 to +175	°C	
TL	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds		300	°C	

Thermal Characteristics

Symbol	Symbol Parameter		Max U	
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case		3.35	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient *		40	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient		62.5	°C/W

^{*} When mounted on the minimum pad size recommended (PCB Mount)

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Cha	racteristics					
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	60			V
ΔBV _{DSS}	Breakdown Voltage Temperature Coefficient	$I_D = 250 \mu A$, Referenced to $25^{\circ}C$		0.06		V/°C
I _{DSS}		V _{DS} = 60 V, V _{GS} = 0 V			1	μΑ
	Zero Gate Voltage Drain Current	V _{DS} = 48 V, T _C = 150°C			10	μΑ
I _{GSSF}	Gate-Body Leakage Current, Forward	V _{GS} = 25 V, V _{DS} = 0 V			100	nA
I _{GSSR}	Gate-Body Leakage Current, Reverse	V _{GS} = -25 V, V _{DS} = 0 V			-100	nA
On Cha	racteristics					•
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$	2.0		4.0	V
R _{DS(on)}	Static Drain-Source On-Resistance	V _{GS} = 10 V, I _D = 6.5 A		0.105	0.135	Ω
9 _{FS}	Forward Transconductance	$V_{DS} = 25 \text{ V}, I_D = 6.5 \text{ A}$ (Note 4)		5.1		S
C _{iss}	Input Capacitance Output Capacitance	$V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V},$ f = 1.0 MHz		240 90	310 120	pF pF
C _{rss}	Reverse Transfer Capacitance			15	20	pF
Switchi	ng Characteristics					
t _{d(on)}	Turn-On Delay Time	V - 20 V I - 6 F A		5	20	ns
t _r	Turn-On Rise Time	$V_{DD} = 30 \text{ V}, I_{D} = 6.5 \text{ A},$ $R_{G} = 25 \Omega$		25	60	ns
t _{d(off)}	Turn-Off Delay Time	NG - 23 12		8	25	ns
t _f	Turn-Off Fall Time	(Note 4, 5)		15	40	ns
Qg	Total Gate Charge	V _{DS} = 48 V, I _D = 13 A,		5.8	7.5	nC
Q _{gs}	Gate-Source Charge	V _{GS} = 10 V		2.0		nC
Q _{gd}	Gate-Drain Charge	(Note 4, 5)		2.5		nC
Drain-S	ource Diode Characteristics a	nd Maximum Ratings				
I _S	Maximum Continuous Drain-Source Did			13	Α	
I _{SM}	Maximum Pulsed Drain-Source Diode Forward Current				52	Α
V _{SD}	Drain-Source Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_{S} = 13 \text{ A}$			1.5	V
t _{rr}	Reverse Recovery Time	$V_{GS} = 0 \text{ V, } I_{S} = 13 \text{ A,}$		39		ns
Q _{rr}	Reverse Recovery Charge	$dI_F / dt = 100 \text{ A/}\mu\text{s}$ (Note 4)		40		nC

- **Notes:**1. Repetitive Rating : Pulse width limited by maximum junction temperature 2. L = 590μH, I_{AS} = 13A, V_{DD} = 25V, R_G = 25 Ω , Starting T_J = 25°C 3. I_{SD} \leq 13A, di/dt \leq 300A/us, V_{DD} \leq BV_{DSS}, Starting T_J = 25°C 4. Pulse Test : Pulse width \leq 300μs, Duty cycle \leq 2% 5. Essentially independent of operating temperature

Typical Characteristics

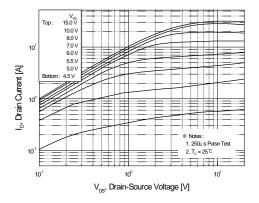


Figure 1. On-Region Characteristics

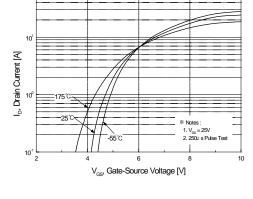


Figure 2. Transfer Characteristics

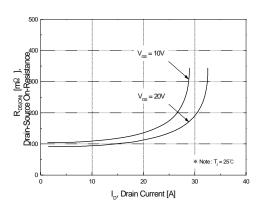


Figure 3. On-Resistance Variation vs.

Drain Current and Gate Voltage

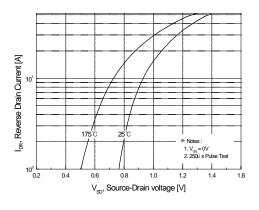


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

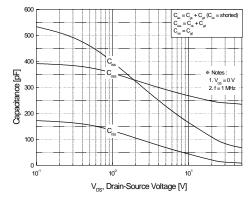


Figure 5. Capacitance Characteristics

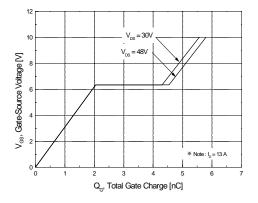
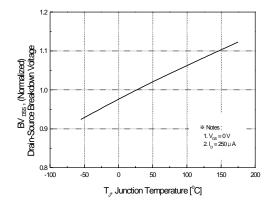


Figure 6. Gate Charge Characteristics

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Typical Characteristics (Continued)



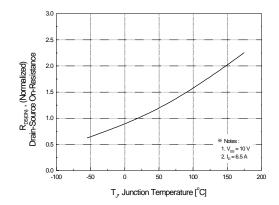
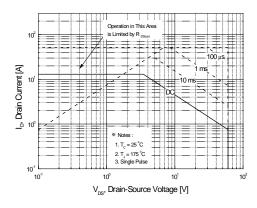


Figure 7. Breakdown Voltage Variation vs. Temperature

Figure 8. On-Resistance Variation vs. Temperature



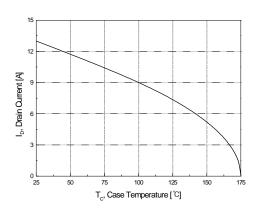


Figure 9. Maximum Safe Operating Area

Figure 10. Maximum Drain Current vs. Case Temperature

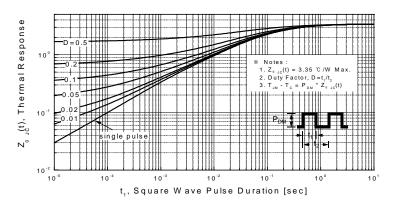
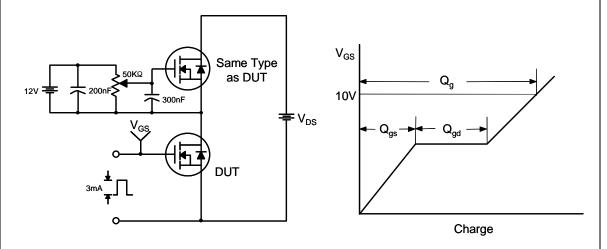


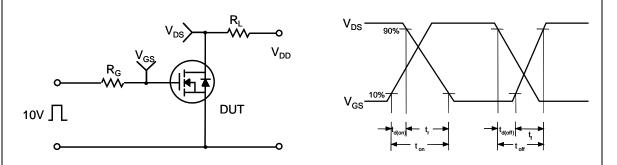
Figure 11. Transient Thermal Response Curve

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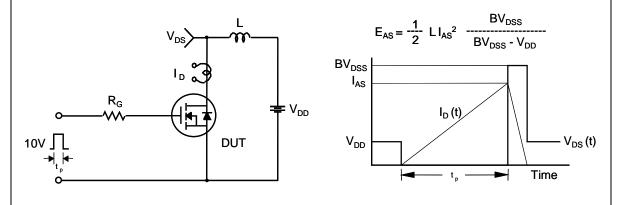
Gate Charge Test Circuit & Waveform



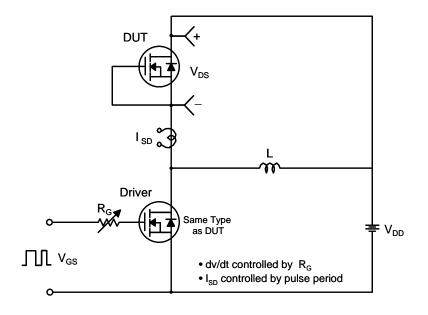
Resistive Switching Test Circuit & Waveforms

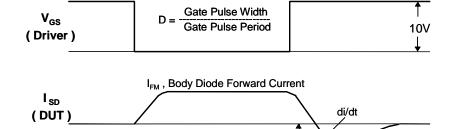


Unclamped Inductive Switching Test Circuit & Waveforms



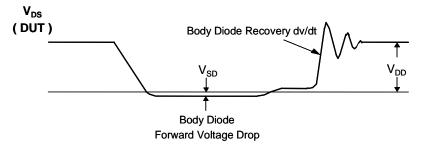
Peak Diode Recovery dv/dt Test Circuit & Waveforms



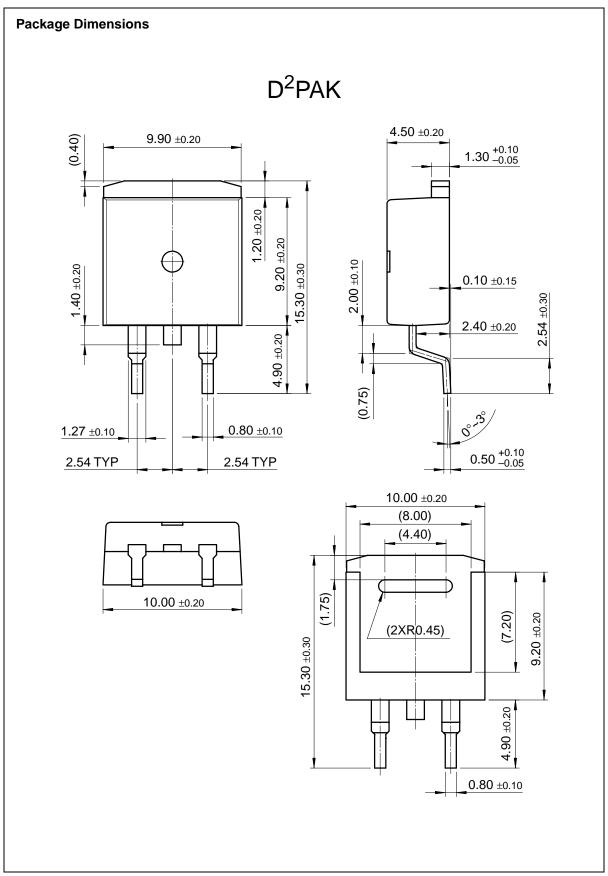


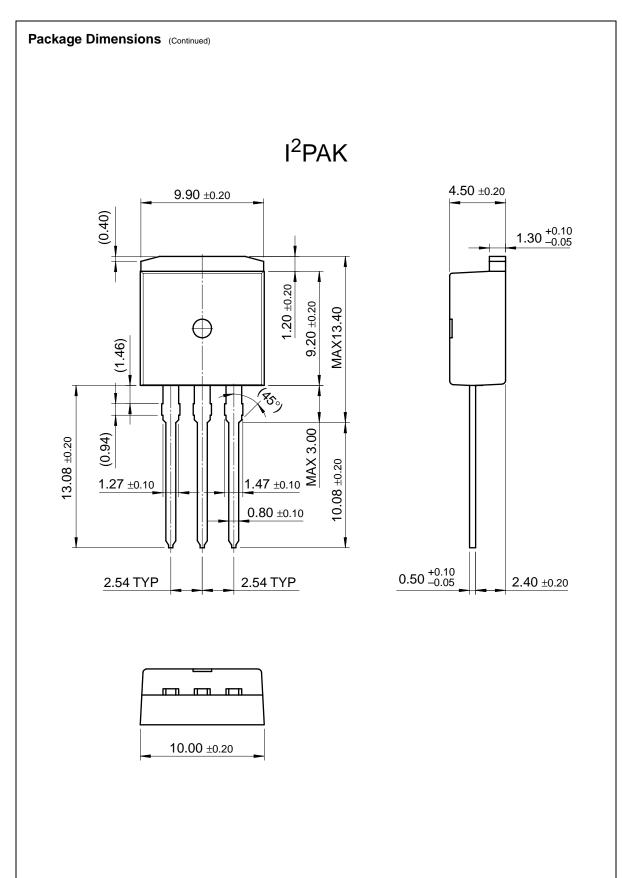
Body Diode Reverse Current

 I_{RM}



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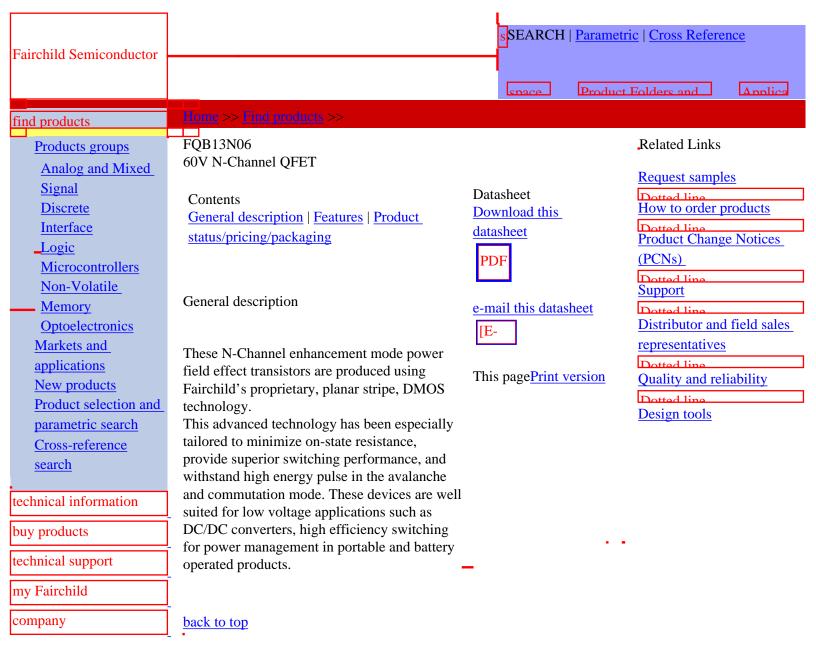
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Features

- 13A, 60V, $R_{DS(on)} = 0.135\Omega$ @ $V_{GS} = 10 \text{ V}$
- Low gate charge (typical 5.8 nC)
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- Fast switching
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- 175°C maximum junction temperature rating

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Product status/pricing/packaging

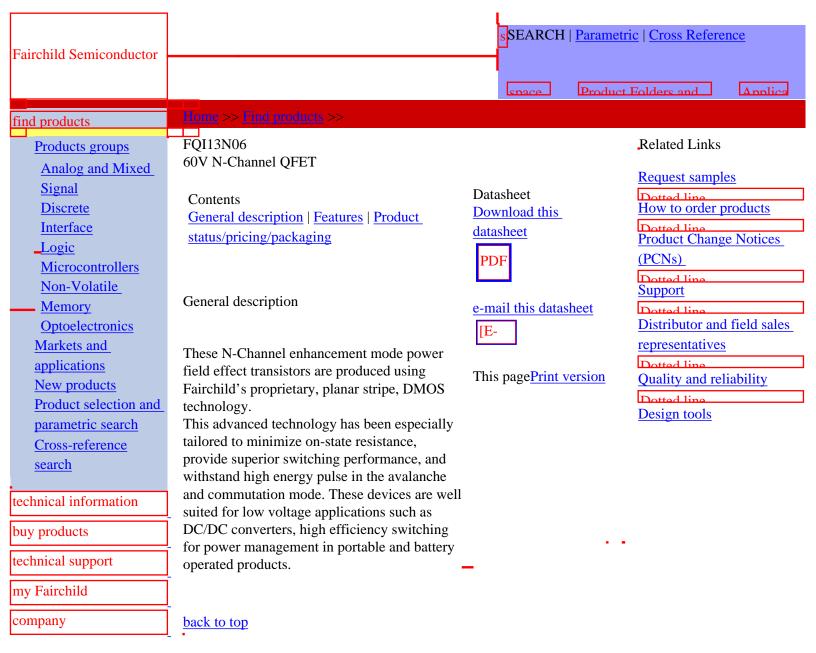
Product	Product status	Pricing*	Package type	Leads	Packing method
FQB13N06TM	Full Production	\$0.471	TO-263(D2PAK)	2	TAPE REEL

^{* 1,000} piece Budgetary Pricing

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Product status/pricing/packaging

Product	Product status	Pricing*	Package type	Leads	Packing method
FQI13N06TU	Full Production	\$0.471	TO-262(I2PAK)	3	RAIL

^{* 1,000} piece Budgetary Pricing

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